



SPECIFICATION

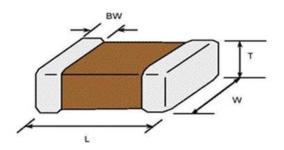
(Reference sheet)

- · Supplier : Samsung electro-mechanics
- · Product : Multi-layer Ceramic Capacitor
- Samsung P/N :
 Description :
- CL21C471KBANNNC CAP, 470pF, 50V, ± 10%, C0G, 0805

A. Samsung Part Number

| | | | <u>CL</u> ① | <mark>21</mark> ② | <u>C</u> 3 | <u>471</u> ④ | <u>K</u> 5 | <u>B</u> 6 | <mark>4</mark> ⑦ | <u>N</u> 8 | <u>N</u> 9 | <u>N</u> 10 | <mark>C</mark> 10 | |
|-------------|--|--------------------|-----------------------|----------------------|---------------|-----------------|---------------|--------------------------|---------------------|---------------|---------------|----------------|--|-----------|
| _ | Series Size | Samsung M 0805 | Multi-lay (inch co | | rami | | | ± 0.10 | mm | | | W: | 1.25 ± 0.10 mm | |
| 3 4 5 | Dielectric Capacitance Capacitance | C0G 470 ± 10 | | | | | 8 | Inner Termi Platin | inatio | | | | Ni Cu Sn 100% | (Pb Free) |
| 6 7 | tolerance Rated Voltage Thickness | 50 0.65 ± 0.10 | V | | | | 9 10 11 | Produ Speci Packa | uct ial | | | | Normal Reserved for fut Cardboard Type | ure use |

B. Structure and dimension



| Samsung P/N | Dimension(mm) | | | | | | | | |
|-----------------|---------------|-------------|-------------|-----------------|--|--|--|--|--|
| (Lead Free) | L | W | Т | BW | | | | | |
| CL21C471KBANNNC | 2.00 ± 0.10 | 1.25 ± 0.10 | 0.65 ± 0.10 | 0.50+0.20/-0.30 | | | | | |

C. Samsung Reliability Test and Judgement condition

| | Performance | Test condition | | | | |
|-------------------|---|--|--|--|--|--|
| Capacitance | Within specified tolerance | 1₩±10% / 0.5~5Vrms | | | | |
| Q | 1,000 min | | | | | |
| Insulation | 10,000Mohm or 500Mohm×µF | Rated Voltage 60~120 sec. | | | | |
| Resistance | Whichever is smaller | | | | | |
| Appearance | No abnormal exterior appearance | Microscop (X10) | | | | |
| Withstanding | No dielectric breakdown or | 300% of the rated voltage | | | | |
| Voltage | mechanical breakdown | | | | | |
| Temperature | COG | | | | | |
| Characteristics | (From -55℃ to 125℃, Capacitance change s | hould be within ±30PPM /ິC) | | | | |
| Adhesive Strength | No peeling shall be occur on the | 500g×F, for 10±1 sec. | | | | |
| of Termination | terminal electrode | | | | | |
| Bending Strength | Capacitance change : | Bending to the limit (1mm) | | | | |
| | within $\pm 5\%$ or ± 0.5 pF whichever is larger | with 1.0mm/sec. | | | | |
| Solderability | More than 75% of terminal surface | SnAg3.0Cu0.5 solder | | | | |
| | is to be soldered newly | 245±5℃, 3±0.3sec. | | | | |
| | | (preheating : 80~120 ℃ for 10~30sec.) | | | | |
| | | | | | | |
| Resistance to | Capacitance change : | Solder pot : 270±5℃, 10±1sec. | | | | |
| Soldering heat | within $\pm 2.5\%$ or $\pm 0.25 \text{ pF}$ whichever is larger | | | | | |
| | Tan δ, IR : initial spec. | | | | | |
| Vibration Test | Capacitance change : | Amplitude : 1.5mm | | | | |
| | within $\pm 2.5\%$ or ± 0.25 pF whichever is larger | From 10Hz to 55Hz (return : 1min.) | | | | |
| | Tan δ, IR : initial spec. | 2hours ´ 3 direction (x, y, z) | | | | |
| Moisture | Capacitance change : | With rated voltage | | | | |
| Resistance | within $\pm 7.5\%$ or $\pm 0.75 \text{ pF}$ whichever is larger | 40±2℃, 90~95%RH, 500+12/-0hrs | | | | |
| | Q: 200 min | | | | | |
| | IR : 500Mohm or 25Mohm × μF | | | | | |
| | Whichever is smaller | | | | | |
| High Temperature | Capacitance change : | With 200% of the rated voltage | | | | |
| Resistance | within $\pm 3\%$ or ± 0.3 pF whichever is larger | Max. operating temperature | | | | |
| | Q: 350 min | 1000+48/-0hrs | | | | |
| | IR : 1,000Mohm or 50Mohm × μF | | | | | |
| | Whichever is smaller | | | | | |
| Temperature | Capacitance change : | 1 cycle condition | | | | |
| Cycling | within $\pm 2.5\%$ or ± 0.25 pF whichever is larger | Min. operating temperature $\rightarrow 25^{\circ}$ C | | | | |
| | Tan δ , IR : initial spec. | \rightarrow Max. operating temperature \rightarrow 25 °C | | | | |
| | , | | | | | |
| | | | | | | |
| | | 5 cycle test | | | | |
| | | 5 cycle test | | | | |

* The reliability test condition can be replaced by the corresponding accelerated test condition.

D. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 °C, 10sec. Max)

Product specifications included in the specifications are effective as of March 1, 2013. Please be advised that they are standard product specifications for reference only. We may change, modify or discontinue the product specifications without notice at any time. So, you need to approve the product specifications before placing an order. Should you have any question regarding the product specifications, please contact our sales personnel or application engineers.

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- 2 Automotive or Transportation equipment (vehicles, trains, ships, etc)
- 3 Medical equipment
- *④ Military equipment*
- *⑤* Disaster prevention/crime prevention equipment
- *ⓐ* Any other applications with the same as or similar complexity or reliability to the applications set forth above.